



Welcome to **E-XFL.COM**

Understanding <u>Embedded - FPGAs (Field Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	234720
Number of Logic Elements/Cells	622000
Total RAM Bits	51200000
Number of I/O	696
Number of Gates	-
Voltage - Supply	0.87V ~ 0.93V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1517-BBGA, FCBGA
Supplier Device Package	1517-FBGA (40x40)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5sgxma7k2f40c1n

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

Recommended Operating Conditions

This section lists the functional operating limits for the AC and DC parameters for Stratix V devices. Table 6 lists the steady-state voltage and current values expected from Stratix V devices. Power supply ramps must all be strictly monotonic, without plateaus.

Table 6. Recommended Operating Conditions for Stratix V Devices (Part 1 of 2)

Symbol	Description	Condition	Min ⁽⁴⁾	Тур	Max ⁽⁴⁾	Unit
	Core voltage and periphery circuitry power supply (C1, C2, I2, and I3YY speed grades)	_	0.87	0.9	0.93	V
V _{CC}	Core voltage and periphery circuitry power supply (C2L, C3, C4, I2L, I3, I3L, and I4 speed grades) (3)	_	0.82	0.85	0.88	V
V _{CCPT}	Power supply for programmable power technology	_	1.45	1.50	1.55	V
V _{CC_AUX}	Auxiliary supply for the programmable power technology	_	2.375	2.5	2.625	V
V (1)	I/O pre-driver (3.0 V) power supply		2.85	3.0	3.15	V
V _{CCPD} ⁽¹⁾	I/O pre-driver (2.5 V) power supply		2.375	2.5	2.625	V
	I/O buffers (3.0 V) power supply	_	2.85	3.0	3.15	٧
	I/O buffers (2.5 V) power supply	_	2.375	2.5	2.625	V
	I/O buffers (1.8 V) power supply	_	1.71	1.8	1.89	٧
V_{CCIO}	I/O buffers (1.5 V) power supply	_	1.425	1.5	1.575	V
	I/O buffers (1.35 V) power supply		1.283	1.35	1.45	V
	I/O buffers (1.25 V) power supply		1.19	1.25	1.31	V
	I/O buffers (1.2 V) power supply	_	1.14	1.2	1.26	V
	Configuration pins (3.0 V) power supply		2.85	3.0	3.15	V
V_{CCPGM}	Configuration pins (2.5 V) power supply	_	2.375	2.5	2.625	V
	Configuration pins (1.8 V) power supply	_	1.71	1.8	1.89	V
V _{CCA_FPLL}	PLL analog voltage regulator power supply		2.375	2.5	2.625	V
V _{CCD_FPLL}	PLL digital voltage regulator power supply		1.45	1.5	1.55	V
V _{CCBAT} (2)	Battery back-up power supply (For design security volatile key register)	_	1.2	_	3.0	V
V _I	DC input voltage	_	-0.5	_	3.6	V
V ₀	Output voltage	_	0	_	V _{CCIO}	V
т.	Operating junction temperature	Commercial	0	_	85	°C
T _J	Operating junction temperature	Industrial	-40	_	100	°C

Table 7. Recommended Transceiver Power Supply Operating Conditions for Stratix V GX, GS, and GT Devices (Part 2 of 2)

Symbol	Description	Devices	Minimum ⁽⁴⁾	Typical	Maximum ⁽⁴⁾	Unit
			0.82	0.85	0.88	
V _{CCR_GXBR}	Receiver analog power supply (right side)	GX, GS, GT	0.87	0.90	0.93	V
(2)	neceiver analog power supply (right side)	ux, us, u1	0.97	1.0	1.03	v
			1.03	1.05	1.07	
V _{CCR_GTBR}	Receiver analog power supply for GT channels (right side)	GT	1.02	1.05	1.08	V
			0.82	0.85	0.88	
V _{CCT_GXBL}	Transmitter analog newer cupply (left side)	GX, GS, GT	0.87	0.90	0.93	V
(2)	Transmitter analog power supply (left side)	ux, us, u1	0.97	1.0	1.03	V
			1.03	1.05	1.07	
			0.82	0.85	0.88	
V _{CCT_GXBR}	Transmitter analog power supply (right side)	GX, GS, GT	0.87	0.90	0.93	V
(2)	Transmitter analog power supply (right side)	ux, us, u1	0.97	1.0	1.03	V
			1.03	1.05	1.07	
V _{CCT_GTBR}	Transmitter analog power supply for GT channels (right side)	GT	1.02	1.05	1.08	V
V _{CCL_GTBR}	Transmitter clock network power supply	GT	1.02	1.05	1.08	V
V _{CCH_GXBL}	Transmitter output buffer power supply (left side)	GX, GS, GT	1.425	1.5	1.575	V
V _{CCH_GXBR}	Transmitter output buffer power supply (right side)	GX, GS, GT	1.425	1.5	1.575	V

Notes to Table 7:

⁽¹⁾ This supply must be connected to 3.0 V if the CMU PLL, receiver CDR, or both, are configured at a base data rate > 6.5 Gbps. Up to 6.5 Gbps, you can connect this supply to either 3.0 V or 2.5 V.

⁽²⁾ Refer to Table 8 to select the correct power supply level for your design.

⁽³⁾ When using ATX PLLs, the supply must be 3.0 V.

⁽⁴⁾ This value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

I/O Pin Leakage Current

Table 9 lists the Stratix V I/O pin leakage current specifications.

Table 9. I/O Pin Leakage Current for Stratix V Devices (1)

Symbol	Description	Conditions	Min	Тур	Max	Unit
I _I	Input pin	$V_I = 0 V to V_{CCIOMAX}$	-30	_	30	μΑ
I _{OZ}	Tri-stated I/O pin	$V_0 = 0 V \text{ to } V_{\text{CCIOMAX}}$	-30		30	μΑ

Note to Table 9:

(1) If $V_0 = V_{CCIO}$ to $V_{CCIOMax}$, 100 μA of leakage current per I/O is expected.

Bus Hold Specifications

Table 10 lists the Stratix V device family bus hold specifications.

Table 10. Bus Hold Parameters for Stratix V Devices

				V _{CCIO}									
Parameter	Symbol	Conditions	1.2	2 V	1.9	5 V	1.8	B V	2.	5 V	3.0	V	Unit
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Low sustaining current	I _{SUSL}	V _{IN} > V _{IL} (maximum)	22.5	_	25.0	_	30.0	_	50.0	_	70.0	_	μА
High sustaining current	I _{SUSH}	V _{IN} < V _{IH} (minimum)	-22.5	_	-25.0	_	-30.0	_	-50.0		-70.0		μА
Low overdrive current	I _{ODL}	0V < V _{IN} < V _{CCIO}	_	120	_	160	_	200	_	300	_	500	μА
High overdrive current	I _{ODH}	0V < V _{IN} < V _{CCIO}	_	-120	_	-160	_	-200	_	-300	_	-500	μА
Bus-hold trip point	V_{TRIP}	_	0.45	0.95	0.50	1.00	0.68	1.07	0.70	1.70	0.80	2.00	V

On-Chip Termination (OCT) Specifications

If you enable OCT calibration, calibration is automatically performed at power-up for I/Os connected to the calibration block. Table 11 lists the Stratix V OCT termination calibration accuracy specifications.

Table 11. OCT Calibration Accuracy Specifications for Stratix V Devices (1) (Part 1 of 2)

				Calibratio	n Accuracy		
Symbol	Description	Conditions	C 1	C2,I2	C3,I3, I3YY	C4,I4	Unit
25-Ω R _S	Internal series termination with calibration (25- Ω setting)	V _{CCIO} = 3.0, 2.5, 1.8, 1.5, 1.2 V	±15	±15	±15	±15	%

			Re	esistance	Tolerance	,	
Symbol	Description	Conditions	C1	C2,I2	C3, I3, I3YY	C4, I4	Unit
50-Ω R _S	Internal series termination without calibration (50- Ω setting)	V _{CCIO} = 1.8 and 1.5 V	±30	±30	±40	±40	%
50-Ω R _S	Internal series termination without calibration (50- Ω setting)	V _{CCIO} = 1.2 V	±35	±35	±50	±50	%
100-Ω R _D	Internal differential termination (100-Ω setting)	V _{CCPD} = 2.5 V	±25	±25	±25	±25	%

Calibration accuracy for the calibrated series and parallel OCTs are applicable at the moment of calibration. When voltage and temperature conditions change after calibration, the tolerance may change.

OCT calibration is automatically performed at power-up for OCT-enabled I/Os. Table 13 lists the OCT variation with temperature and voltage after power-up calibration. Use Table 13 to determine the OCT variation after power-up calibration and Equation 1 to determine the OCT variation without recalibration.

Equation 1. OCT Variation Without Recalibration for Stratix V Devices (1), (2), (3), (4), (5), (6)

$$R_{OCT} = R_{SCAL} \Big(1 + \langle \frac{dR}{dT} \times \Delta T \rangle \pm \langle \frac{dR}{dV} \times \Delta V \rangle \Big)$$

Notes to Equation 1:

- (1) The R_{OCT} value shows the range of OCT resistance with the variation of temperature and V_{CCIO} .
- (2) R_{SCAL} is the OCT resistance value at power-up.
- (3) ΔT is the variation of temperature with respect to the temperature at power-up.
- (4) ΔV is the variation of voltage with respect to the V_{CCIO} at power-up.
- (5) dR/dT is the percentage change of R_{SCAL} with temperature.
- (6) dR/dV is the percentage change of R_{SCAL} with voltage.

Table 13 lists the on-chip termination variation after power-up calibration.

Table 13. OCT Variation after Power-Up Calibration for Stratix V Devices (Part 1 of 2) (1)

Symbol	Description	V _{CCIO} (V)	Typical	Unit
	dR/dV OCT variation with voltage without recalibration	3.0	0.0297	
		2.5	0.0344	
dR/dV		1.8	0.0499	%/mV
		1.5	0.0744	
		1.2	0.1241	

Page 12 Electrical Characteristics

Table 13. OCT Variation after Power-Up Calibration for Stratix V Devices (Part 2 of 2) (1)

Symbol	Description	V _{CCIO} (V)	Typical	Unit
		3.0	0.189	
	OCT variation with temperature without recalibration	2.5	0.208	%/°C
dR/dT		1.8	0.266	
		1.5	0.273	1
		1.2	0.317	

Note to Table 13:

(1) Valid for a V_{CCIO} range of $\pm 5\%$ and a temperature range of 0° to $85^\circ\text{C}.$

Pin Capacitance

Table 14 lists the Stratix V device family pin capacitance.

Table 14. Pin Capacitance for Stratix V Devices

Symbol	ol Description		Unit
C _{IOTB}	Input capacitance on the top and bottom I/O pins	6	pF
C _{IOLR}	Input capacitance on the left and right I/O pins	6	pF
C _{OUTFB}	Input capacitance on dual-purpose clock output and feedback pins	6	pF

Hot Socketing

Table 15 lists the hot socketing specifications for Stratix V devices.

Table 15. Hot Socketing Specifications for Stratix V Devices

Symbol	Description	Maximum
I _{IOPIN (DC)}	DC current per I/O pin	300 μΑ
I _{IOPIN (AC)}	AC current per I/O pin	8 mA ⁽¹⁾
I _{XCVR-TX (DC)}	DC current per transceiver transmitter pin	100 mA
I _{XCVR-RX (DC)}	DC current per transceiver receiver pin	50 mA

Note to Table 15:

(1) The I/O ramp rate is 10 ns or more. For ramp rates faster than 10 ns, $|I_{IOPIN}| = C dv/dt$, in which C is the I/O pin capacitance and dv/dt is the slew rate.

Page 16 Electrical Characteristics

Table 21. Differential HSTL and HSUL I/O Standards for Stratix V Devices (Part 2 of 2)

I/O		V _{CCIO} (V) V _{DIF(DC)} (V)		V _{X(AC)} (V)				V _{CM(DC)} (V)	V _{DIF(AC)} (V)			
Standard	Min	Тур	Max	Min	Max	Min	Тур	Max	Min	Тур	Max	Min	Max
HSTL-12 Class I, II	1.14	1.2	1.26	0.16	V _{CCIO} + 0.3	_	0.5* V _{CCIO}	_	0.4* V _{CCIO}	0.5* V _{CCIO}	0.6* V _{CCIO}	0.3	V _{CCIO} + 0.48
HSUL-12	1.14	1.2	1.3	0.26	0.26	0.5*V _{CCIO} - 0.12	0.5* V _{CCIO}	0.5*V _{CCIO} + 0.12	0.4* V _{CCIO}	0.5* V _{CCIO}	0.6* V _{CCIO}	0.44	0.44

Table 22. Differential I/O Standard Specifications for Stratix V Devices (7)

I/O	Vc	_{CIO} (V)	(10)	V _{ID} (mV) ⁽⁸⁾				$V_{ICM(DC)}$ (V)		V _{OD} (V) ⁽⁶⁾			V _{OCM} (V) ⁽⁶⁾		
Standard	Min	Тур	Max	Min	Condition	Max	Min	Condition	Max	Min	Тур	Max	Min	Тур	Max
PCML	Trar	nsmitte						of the high-s I/O pin speci							. For
2.5 V	2.375	2.5	2.625	100	V _{CM} =	_	0.05	D _{MAX} ≤ 700 Mbps	1.8	0.247		0.6	1.125	1.25	1.375
LVDS (1)	2.373	2.3	2.023	100	1.25 V		1.05	D _{MAX} > 700 Mbps	1.55	0.247	_	0.6	1.125	1.25	1.375
BLVDS (5)	2.375	2.5	2.625	100	_	_	_	_	_	_	_	_	_		_
RSDS (HIO) ⁽²⁾	2.375	2.5	2.625	100	V _{CM} = 1.25 V	_	0.3	_	1.4	0.1	0.2	0.6	0.5	1.2	1.4
Mini- LVDS (HIO) (3)	2.375	2.5	2.625	200	_	600	0.4	_	1.325	0.25	_	0.6	1	1.2	1.4
LVPECL (4	_	_	_	300	_	_	0.6	D _{MAX} ≤ 700 Mbps	1.8	_	_	_	_	_	_
), (9)	_	_	_	300	_	_	1	D _{MAX} > 700 Mbps	1.6	_	_	_	_	_	_

Notes to Table 22:

- (1) For optimized LVDS receiver performance, the receiver voltage input range must be between 1.0 V to 1.6 V for data rates above 700 Mbps, and 0 V to 1.85 V for data rates below 700 Mbps.
- (2) For optimized RSDS receiver performance, the receiver voltage input range must be between 0.25 V to 1.45 V.
- (3) For optimized Mini-LVDS receiver performance, the receiver voltage input range must be between 0.3 V to 1.425 V.
- (4) For optimized LVPECL receiver performance, the receiver voltage input range must be between 0.85 V to 1.75 V for data rate above 700 Mbps and 0.45 V to 1.95 V for data rate below 700 Mbps.
- (5) There are no fixed V_{ICM} , V_{OD} , and V_{OCM} specifications for BLVDS. They depend on the system topology.
- (6) RL range: $90 \le RL \le 110 \Omega$.
- (7) The 1.4-V and 1.5-V PCML transceiver I/O standard specifications are described in "Transceiver Performance Specifications" on page 18.
- (8) The minimum VID value is applicable over the entire common mode range, VCM.
- (9) LVPECL is only supported on dedicated clock input pins.
- (10) Differential inputs are powered by VCCPD which requires 2.5 $\rm V.$

Power Consumption

Altera offers two ways to estimate power consumption for a design—the Excel-based Early Power Estimator and the Quartus[®] II PowerPlay Power Analyzer feature.

Page 18 Switching Characteristics

Switching Characteristics

This section provides performance characteristics of the Stratix V core and periphery blocks.

These characteristics can be designated as Preliminary or Final.

- Preliminary characteristics are created using simulation results, process data, and other known parameters. The title of these tables show the designation as "Preliminary."
- Final numbers are based on actual silicon characterization and testing. The numbers reflect the actual performance of the device under worst-case silicon process, voltage, and junction temperature conditions. There are no designations on finalized tables.

Transceiver Performance Specifications

This section describes transceiver performance specifications.

Table 23 lists the Stratix V GX and GS transceiver specifications.

Table 23. Transceiver Specifications for Stratix V GX and GS Devices (1) (Part 1 of 7)

Symbol/	Conditions	Trai	nsceive Grade	r Speed 1	Trar	sceive Grade	r Speed 2	Trar	Unit		
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
Reference Clock											
Supported I/O Standards										/DS, and	
Statiuatus	RX reference clock pin			1.4-V PCMI	_, 1.5-V	PCML,	2.5-V PCM	L, LVPE	CL, and	d LVDS	
Input Reference Clock Frequency (CMU PLL) (8)	_	40	_	710	40	_	710	40	_	710	MHz
Input Reference Clock Frequency (ATX PLL) (8)	_	100	_	710	100	_	710	100	_	710	MHz
Rise time	Measure at ±60 mV of differential signal ⁽²⁶⁾	_	_	400	_	_	400	_	_	400	ne
Fall time	Measure at ±60 mV of differential signal ⁽²⁶⁾	_	_	400	_	_	400	_	_	400	ps
Duty cycle	_	45		55	45	_	55	45		55	%
Spread-spectrum modulating clock frequency	PCI Express® (PCIe®)	30	_	33	30	_	33	30	_	33	kHz

Page 20 Switching Characteristics

Table 23. Transceiver Specifications for Stratix V GX and GS Devices (1) (Part 3 of 7)

Symbol/	Conditions	Trai	nsceive Grade	r Speed 1	Trai	sceive Grade	r Speed 2	Trar	er Speed e 3	Unit	
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
Reconfiguration clock (mgmt_clk_clk) frequency	_	100	_	125	100	_	125	100	_	125	MHz
Receiver											
Supported I/O Standards	_			1.4-V PCMI	_, 1.5-V	PCML,	2.5-V PCM	L, LVPE	CL, and	d LVDS	
Data rate (Standard PCS)	_	600	_	12200	600		12200	600	_	8500/ 10312.5 (24)	Mbps
Data rate (10G PCS) (9), (23)	_	600	_	14100	600	_	12500	600	_	8500/ 10312.5 (24)	Mbps
Absolute V _{MAX} for a receiver pin ⁽⁵⁾	_	_	_	1.2	_	_	1.2	_	_	1.2	V
Absolute V _{MIN} for a receiver pin	_	-0.4	_	_	-0.4	_	_	-0.4	_	_	V
Maximum peak- to-peak differential input voltage V _{ID} (diff p- p) before device configuration (22)	_	_	_	1.6	_	_	1.6	_	_	1.6	V
Maximum peak- to-peak	$V_{CCR_GXB} = 1.0 \text{ V}/1.05 \text{ V} $ $(V_{ICM} = 0.70 \text{ V})$	_	_	2.0	_	_	2.0	_	_	2.0	V
differential input voltage V _{ID} (diff p-p) after device configuration (18),	$V_{\text{CCR_GXB}} = 0.90 \text{ V}$ $(V_{\text{ICM}} = 0.6 \text{ V})$			2.4	_		2.4	_	_	2.4	V
(22)	$V_{\text{CCR_GXB}} = 0.85 \text{ V}$ $(V_{\text{ICM}} = 0.6 \text{ V})$	_	_	2.4	_	_	2.4	_	_	2.4	V
Minimum differential eye opening at receiver serial input pins (6), (22), (27)	_	85	_	_	85	_	_	85	_	_	mV

Page 22 Switching Characteristics

Table 23. Transceiver Specifications for Stratix V GX and GS Devices (1) (Part 5 of 7)

Symbol/	Conditions	Tra	nsceive Grade	r Speed 1	Trai	nsceive Grade	r Speed 2	Trai	r Speed 3	Unit	
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
	DC Gain Setting = 0	_	0	_	_	0	_	_	0	_	dB
	DC Gain Setting = 1	_	2	_	_	2	_	_	2	_	dB
Programmable DC gain	DC Gain Setting = 2		4	_	_	4		_	4	_	dB
	DC Gain Setting = 3		6		_	6	_	_	6	_	dB
	DC Gain Setting = 4	_	8		_	8		_	8	_	dB
Transmitter											
Supported I/O Standards	_		1.4-V and 1.5-V PCML								
Data rate (Standard PCS)	_	600	_	12200	600		12200	600	_	8500/ 10312.5 (24)	Mbps
Data rate (10G PCS)	_	600	_	14100	600	_	12500	600	_	8500/ 10312.5 (24)	Mbps
	85-Ω setting	_	85 ± 20%	_	_	85 ± 20%	_	_	85 ± 20%	_	Ω
Differential on-	100-Ω setting		100 ± 20%	_	_	100 ± 20%		_	100 ± 20%	_	Ω
chip termination resistors	120-Ω setting	_	120 ± 20%	_	_	120 ± 20%	_	_	120 ± 20%	_	Ω
	150-Ω setting	_	150 ± 20%	_	_	150 ± 20%	_	_	150 ± 20%	_	Ω
V _{OCM} (AC coupled)	0.65-V setting	_	650	_	_	650	_	_	650	_	mV
V _{OCM} (DC coupled)	_	_	650	_	_	650	_	_	650	_	mV
Rise time (7)	20% to 80%	30	_	160	30	_	160	30		160	ps
Fall time ⁽⁷⁾	80% to 20%	30	_	160	30		160	30	_	160	ps
Intra-differential pair skew	Tx V _{CM} = 0.5 V and slew rate of 15 ps	_	_	15	_	_	15	_	_	15	ps
Intra-transceiver block transmitter channel-to- channel skew	x6 PMA bonded mode	_	_	120	_	_	120	_	_	120	ps

Page 30 Switching Characteristics

Table 28. Transceiver Specifications for Stratix V GT Devices (Part 1 of 5) $^{(1)}$

Symbol/	Conditions	5	Transceive Speed Grade			Transceive peed Grade		Unit
Description		Min	Тур	Max	Min	Тур	Max	
Reference Clock	•	•	•	•	•	•	•	
Supported I/O Standards	Dedicated reference clock pin	1.2-V PCN	/IL, 1.4-V PC	ML, 1.5-V P	CML, 2.5-V and HCSL	PCML, Diffe	rential LVPE	ECL, LVDS,
Standards	RX reference clock pin		1.4-V PCML	., 1.5-V PCN	IL, 2.5-V PC	ML, LVPEC	L, and LVDS	;
Input Reference Clock Frequency (CMU PLL) ⁽⁶⁾	_	40	_	710	40	_	710	MHz
Input Reference Clock Frequency (ATX PLL) (6)	_	100	_	710	100	_	710	MHz
Rise time	20% to 80%	_	_	400	_	_	400	
Fall time	80% to 20%	_	_	400	_	<u> </u>	400	ps
Duty cycle	_	45	_	55	45	_	55	%
Spread-spectrum modulating clock frequency	PCI Express (PCIe)	30	_	33	30	_	33	kHz
Spread-spectrum downspread	PCle	_	0 to -0.5	_	_	0 to -0.5	_	%
On-chip termination resistors (19)	_	_	100	_	_	100	_	Ω
Absolute V _{MAX} (3)	Dedicated reference clock pin	_	_	1.6	_	_	1.6	V
	RX reference clock pin	_	_	1.2	_	_	1.2	
Absolute V _{MIN}	_	-0.4	_	_	-0.4	_	_	V
Peak-to-peak differential input voltage	_	200	_	1600	200	_	1600	mV
V _{ICM} (AC coupled)	Dedicated reference clock pin		1050/1000	2)		1050/1000	2)	mV
	RX reference clock pin	1	.0/0.9/0.85	(22)	1	.0/0.9/0.85	(22)	V
V _{ICM} (DC coupled)	HCSL I/O standard for PCIe reference clock	250	_	550	250	_	550	mV

Switching Characteristics Page 31

Table 28. Transceiver Specifications for Stratix V GT Devices (Part 2 of 5) $^{(1)}$

Symbol/	Conditions	S	Transceive peed Grade			Transceive Deed Grade		Unit
Description		Min	Тур	Max	Min	Тур	Max	1
	100 Hz	_	_	-70	_	_	-70	
Transmitter REFCLK	1 kHz	_	_	-90		_	-90	
Phase Noise (622	10 kHz	_	_	-100	_	_	-100	dBc/Hz
MHz) ⁽¹⁸⁾	100 kHz	_	_	-110	_	_	-110	
	≥1 MHz		_	-120	_		-120	1
Transmitter REFCLK Phase Jitter (100 MHz) ⁽¹⁵⁾	10 kHz to 1.5 MHz (PCle)	_	_	3	_	_	3	ps (rms)
RREF (17)	_	_	1800 ± 1%	_	_	1800 ± 1%	_	Ω
Transceiver Clocks								
fixedclk clock frequency	PCIe Receiver Detect	_	100 or 125	_	_	100 or 125	_	MHz
Reconfiguration clock (mgmt_clk_clk) frequency		100	_	125	100		125	MHz
Receiver								
Supported I/O Standards	_		1.4-V PCML	, 1.5-V PCML	_, 2.5-V PCI	ML, LVPEC	L, and LVDS	6
Data rate (Standard PCS) (21)	GX channels	600	_	8500	600	_	8500	Mbps
Data rate (10G PCS) (21)	GX channels	600	_	12,500	600	_	12,500	Mbps
Data rate	GT channels	19,600	_	28,050	19,600	_	25,780	Mbps
Absolute V _{MAX} for a receiver pin ⁽³⁾	GT channels	_	_	1.2	_	_	1.2	V
Absolute V _{MIN} for a receiver pin	GT channels	-0.4	_	_	-0.4	_	_	V
Maximum peak-to-peak	GT channels		_	1.6	_		1.6	V
differential input voltage V _{ID} (diff p-p) before device configuration ⁽²⁰⁾	GX channels				(8)			
	GT channels							
Maximum peak-to-peak differential input voltage V _{ID} (diff p-p) after device configuration (16), (20)	$V_{CCR_GTB} = 1.05 \text{ V} $ $(V_{ICM} = 0.65 \text{ V})$	_	_	2.2	_	_	2.2	V
oomiguration ', ' /	GX channels				(8)		•	•
Minimum differential	GT channels	200	_	_	200		_	mV
eye opening at receiver serial input pins ⁽⁴⁾ , ⁽²⁰⁾	GX channels				(8)			

Page 38 Switching Characteristics

- XFI
- ASI
- HiGig/HiGig+
- HiGig2/HiGig2+
- Serial Data Converter (SDC)
- GPON
- SDI
- SONET
- Fibre Channel (FC)
- PCIe
- QPI
- SFF-8431

Download the Stratix V Characterization Report Tool to view the characterization report summary for these protocols.

Core Performance Specifications

This section describes the clock tree, phase-locked loop (PLL), digital signal processing (DSP), memory blocks, configuration, and JTAG specifications.

Clock Tree Specifications

Table 30 lists the clock tree specifications for Stratix V devices.

Table 30. Clock Tree Performance for Stratix V Devices (1)

		Performance		
Symbol	C1, C2, C2L, I2, and I2L	C3, I3, I3L, and I3YY	C4, I4	Unit
Global and Regional Clock	717	650	580	MHz
Periphery Clock	550	500	500	MHz

Note to Table 30:

(1) The Stratix V ES devices are limited to 600 MHz core clock tree performance.

Switching Characteristics Page 45

Table 36. High-Speed I/O Specifications for Stratix V Devices (1), (2) (Part 2 of 4)

Combal	Conditions		C1		C2,	C2L, I	2, I2L	C3, I3, I3L, I3YY			Y C4,14			II.a.i.k
Symbol	Conditions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
Transmitter														
	SERDES factor J = 3 to 10 (9), (11), (12), (13), (14), (15), (16)	(6)	_	1600	(6)	_	1434	(6)	_	1250	(6)	_	1050	Mbps
True Differential I/O Standards	SERDES factor J ≥ 4 LVDS TX with DPA (12), (14), (15), (16)	(6)	_	1600	(6)	_	1600	(6)	_	1600	(6)		1250	Mbps
- f _{HSDR} (data rate)	SERDES factor J = 2, uses DDR Registers	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	Mbps
	SERDES factor J = 1, uses SDR Register	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	Mbps
Emulated Differential I/O Standards with Three External Output Resistor Networks - f _{HSDR} (data rate) (10)	SERDES factor J = 4 to 10 (17)	(6)	_	1100	(6)	_	1100	(6)	_	840	(6)		840	Mbps
t _{x Jitter} - True Differential	Total Jitter for Data Rate 600 Mbps - 1.25 Gbps	_	_	160	_	_	160	_	_	160	_	_	160	ps
I/O Standards	Total Jitter for Data Rate < 600 Mbps	_	_	0.1	_	_	0.1	_	_	0.1	_	_	0.1	UI
t _{x Jitter} - Emulated Differential I/O Standards	Total Jitter for Data Rate 600 Mbps - 1.25 Gbps	_	_	300	_	_	300	_	_	300	_	_	325	ps
with Three External Output Resistor Network	Total Jitter for Data Rate < 600 Mbps	_	_	0.2	_	_	0.2	_	_	0.2	_	_	0.25	UI

Configuration Specification Page 53

Table 46.	JTAG Timino	Parameters a	nd Values	for Stratix V Devices
-----------	-------------	--------------	-----------	-----------------------

Symbol	Description	Min	Max	Unit
t _{JPH}	JTAG port hold time	5	_	ns
t _{JPCO}	JTAG port clock to output	_	11 ⁽¹⁾	ns
t _{JPZX}	JTAG port high impedance to valid output	_	14 ⁽¹⁾	ns
t _{JPXZ}	JTAG port valid output to high impedance	_	14 ⁽¹⁾	ns

Notes to Table 46:

- (1) A 1 ns adder is required for each V_{CCIO} voltage step down from 3.0 V. For example, t_{JPCO} = 12 ns if V_{CCIO} of the TDO I/O bank = 2.5 V, or 13 ns if it equals 1.8 V.
- (2) The minimum TCK clock period is 167 ns if VCCBAT is within the range 1.2V-1.5V when you perform the volatile key programming.

Raw Binary File Size

For the POR delay specification, refer to the "POR Delay Specification" section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices".

Table 47 lists the uncompressed raw binary file (.rbf) sizes for Stratix V devices.

Table 47. Uncompressed .rbf Sizes for Stratix V Devices

Family	Device	Package	Configuration .rbf Size (bits)	IOCSR .rbf Size (bits) (4), (5)
	ECCVAO	H35, F40, F35 ⁽²⁾	213,798,880	562,392
	5SGXA3	H29, F35 ⁽³⁾	137,598,880	564,504
	5SGXA4	_	213,798,880	563,672
	5SGXA5	_	269,979,008	562,392
	5SGXA7	_	269,979,008	562,392
Stratix V GX	5SGXA9	_	342,742,976	700,888
	5SGXAB	_	342,742,976	700,888
	5SGXB5	_	270,528,640	584,344
	5SGXB6	_	270,528,640	584,344
	5SGXB9	_	342,742,976	700,888
	5SGXBB	_	342,742,976	700,888
Chrotin V CT	5SGTC5	_	269,979,008	562,392
Stratix V GT	5SGTC7	_	269,979,008	562,392
	5SGSD3	_	137,598,880	564,504
	FCCCD4	F1517	213,798,880	563,672
Ctrativ V CC	5SGSD4	_	137,598,880	564,504
Stratix V GS	5SGSD5	_	213,798,880	563,672
	5SGSD6	_	293,441,888	565,528
	5SGSD8	_	293,441,888	565,528

Configuration Specification Page 59

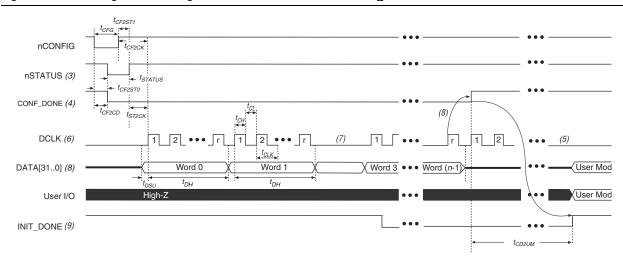


Figure 13. FPP Configuration Timing Waveform When the DCLK-to-DATA[] Ratio is >1 (1), (2)

Notes to Figure 13:

- (1) Use this timing waveform and parameters when the DCLK-to-DATA [] ratio is >1. To find out the DCLK-to-DATA [] ratio for your system, refer to Table 49 on page 55.
- (2) The beginning of this waveform shows the device in user mode. In user mode, nconfig, nstatus, and conf_done are at logic high levels. When nconfig is pulled low, a reconfiguration cycle begins.
- (3) After power-up, the Stratix V device holds nSTATUS low for the time as specified by the POR delay.
- (4) After power-up, before and during configuration, CONF DONE is low.
- (5) Do not leave DCLK floating after configuration. You can drive it high or low, whichever is more convenient.
- (6) "r" denotes the DCLK-to-DATA[] ratio. For the DCLK-to-DATA[] ratio based on the decompression and the design security feature enable settings, refer to Table 49 on page 55.
- (7) If needed, pause DCLK by holding it low. When DCLK restarts, the external host must provide data on the DATA [31..0] pins prior to sending the first DCLK rising edge.
- (8) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF_DONE is released high after the Stratix V device receives all the configuration data successfully. After CONF_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (9) After the option bit to enable the INIT DONE pin is configured into the device, the INIT DONE goes low.

Configuration Specification Page 61

Active Serial Configuration Timing

Table 52 lists the DCLK frequency specification in the AS configuration scheme.

Table 52. DCLK Frequency Specification in the AS Configuration Scheme (1), (2)

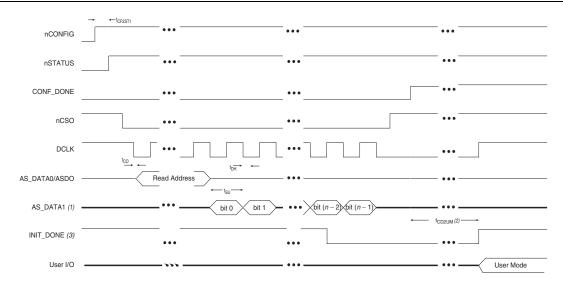
Minimum	Typical	Maximum	Unit
5.3	7.9	12.5	MHz
10.6	15.7	25.0	MHz
21.3	31.4	50.0	MHz
42.6	62.9	100.0	MHz

Notes to Table 52:

- (1) This applies to the DCLK frequency specification when using the internal oscillator as the configuration clock source.
- (2) The AS multi-device configuration scheme does not support DCLK frequency of 100 MHz.

Figure 14 shows the single-device configuration setup for an AS ×1 mode.

Figure 14. AS Configuration Timing



Notes to Figure 14:

- (1) If you are using AS ×4 mode, this signal represents the AS_DATA [3..0] and EPCQ sends in 4-bits of data for each DCLK cycle.
- (2) The initialization clock can be from internal oscillator or ${\tt CLKUSR}$ pin.
- (3) After the option bit to enable the $INIT_DONE$ pin is configured into the device, the $INIT_DONE$ goes low.

Table 53 lists the timing parameters for AS $\times 1$ and AS $\times 4$ configurations in Stratix V devices.

Table 53. AS Timing Parameters for AS \times 1 and AS \times 4 Configurations in Stratix V Devices (1), (2) (Part 1 of 2)

Symbol	Parameter	Minimum	Maximum	Units
t _{CO}	DCLK falling edge to AS_DATAO/ASDO output	_	2	ns
t _{SU}	Data setup time before falling edge on DCLK	1.5	_	ns
t _H	Data hold time after falling edge on DCLK	0	_	ns

Page 62 Configuration Specification

Table 53. AS Timing Parameters for AS \times 1 and AS \times 4 Configurations in Stratix V Devices (1), (2) (Part 2 of 2)

Symbol	Parameter	Minimum	Maximum	Units
t _{CD2UM}	CONF_DONE high to user mode (3)	175	437	μS
t _{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	_	_
t _{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	t_{CD2CU} + (8576 \times CLKUSR period)	_	_

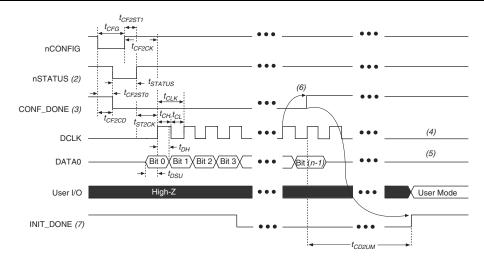
Notes to Table 53:

- (1) The minimum and maximum numbers apply only if you choose the internal oscillator as the clock source for initializing the device.
- $(2) \quad t_{\text{CF2CD}}, t_{\text{CF2ST0}}, t_{\text{CFG}}, t_{\text{STATUS}}, \text{ and } t_{\text{CF2ST1}} \text{ timing parameters are identical to the timing parameters for PS mode listed in Table 54 on page 63}.$
- (3) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on this pin, refer to the Initialization section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.

Passive Serial Configuration Timing

Figure 15 shows the timing waveform for a passive serial (PS) configuration when using a MAX II device, MAX V device, or microprocessor as an external host.

Figure 15. PS Configuration Timing Waveform (1)



Notes to Figure 15:

- (1) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF_DONE are at logic high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
- (2) After power-up, the Stratix V device holds nSTATUS low for the time of the POR delay.
- (3) After power-up, before and during configuration, CONF DONE is low.
- (4) Do not leave DCLK floating after configuration. You can drive it high or low, whichever is more convenient.
- (5) DATAO is available as a user I/O pin after configuration. The state of this pin depends on the dual-purpose pin settings in the **Device and Pins Option**.
- (6) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF_DONE is released high after the Stratix V device receives all the configuration data successfully. After CONF_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (7) After the option bit to enable the INIT DONE pin is configured into the device, the INIT DONE goes low.

Page 66 Glossary

Table 60. Glossary (Part 2 of 4)

Letter	Subject	Definitions	
G			
Н	_	-	
1			
J	J TAG Timing Specifications	High-speed I/O block—Deserialization factor (width of parallel data bus). JTAG Timing Specifications: TMS TDI TCK TJPSU TJ	
K L M N	_		
P	PLL Specifications	Diagram of PLL Specifications (1) CLKOUT Pins Four Core Clock Reconfigurable in User Mode External Feedback Note: (1) Core Clock can only be fed by dedicated clock input pins or PLL outputs.	
Q	_	<u> </u>	
R	R _L	Receiver differential input discrete resistor (external to the Stratix V device).	
		receiver universitial input discrete resistor (external to the otratix v device).	

Glossary Page 67

Table 60. Glossary (Part 3 of 4)

Letter	Subject	Definitions		
	SW (sampling window)	Timing Diagram—the period of time during which the data must be valid in order to capture it correctly. The setup and hold times determine the ideal strobe position within the sampling window, as shown: Bit Time 0.5 x TCCS RSKM Sampling Window (SW) 0.5 x TCCS		
S	Single-ended voltage referenced I/O standard	The JEDEC standard for SSTL and HSTL I/O defines both the AC and DC input signal values. The AC values indicate the voltage levels at which the receiver must meet its timing specifications. The DC values indicate the voltage levels at which the final logic state of the receiver is unambiguously defined. After the receiver input has crossed the AC value, the receiver changes to the new logic state. The new logic state is then maintained as long as the input stays beyond the DC threshold. This approach is intended to provide predictable receiver timing in the presence of input waveform ringing: Single-Ended Voltage Referenced I/O Standard VIHACO VIHACO VILLOCO V		
	t _C	High-speed receiver and transmitter input and output clock period.		
	TCCS (channel- to-channel-skew)	The timing difference between the fastest and slowest output edges, including $t_{\rm CO}$ variation and clock skew, across channels driven by the same PLL. The clock is included in the TCCS measurement (refer to the <i>Timing Diagram</i> figure under SW in this table).		
		High-speed I/O block—Duty cycle on the high-speed transmitter output clock.		
Т	t _{DUTY}	Timing Unit Interval (TUI) The timing budget allowed for skew, propagation delays, and the data sampling window. (TUI = $1/(\text{receiver input clock frequency multiplication factor}) = t_{\text{C}}/w$)		
	t _{FALL}	Signal high-to-low transition time (80-20%) Cycle-to-cycle jitter tolerance on the PLL clock input.		
	t _{INCCJ}			
	t _{OUTPJ_IO}	Period jitter on the general purpose I/O driven by a PLL.		
	t _{OUTPJ_DC}	Period jitter on the dedicated clock output driven by a PLL.		
	t _{RISE}	Signal low-to-high transition time (20-80%)		
U	_	_		

Document Revision History Page 69

Document Revision History

Table 61 lists the revision history for this chapter.

Table 61. Document Revision History (Part 1 of 3)

Date	Version	Changes	
June 2018	3.9	■ Added the "Stratix V Device Overshoot Duration" figure.	
	3.8	■ Added a footnote to the "High-Speed I/O Specifications for Stratix V Devices" table.	
		■ Changed the minimum value for t _{CD2UMC} in the "PS Timing Parameters for Stratix V Devices" table.	
		■ Changed the condition for 100-Ω R _D in the "OCT Without Calibration Resistance Tolerance Specifications for Stratix V Devices" table.	
April 2017		■ Changed the minimum value for t _{CD2UMC} in the "AS Timing Parameters for AS '1 and AS '4 Configurations in Stratix V Devices" table	
		■ Changed the minimum value for t _{CD2UMC} in the "FPP Timing Parameters for Stratix V Devices When the DCLK-to-DATA[] Ratio is >1" table.	
		■ Changed the minimum value for t _{CD2UMC} in the "FPP Timing Parameters for Stratix V Devices When the DCLK-to-DATA[] Ratio is >1" table.	
		■ Changed the minimum number of clock cycles value in the "Initialization Clock Source Option and the Maximum Frequency" table.	
June 2016	3.7	■ Added the V _{ID} minimum specification for LVPECL in the "Differential I/O Standard Specifications for Stratix V Devices" table	
		■ Added the I _{OUT} specification to the "Absolute Maximum Ratings for Stratix V Devices" table.	
December 2015	3.6	■ Added a footnote to the "High-Speed I/O Specifications for Stratix V Devices" table.	
December 2015	3.5	■ Changed the transmitter, receiver, and ATX PLL data rate specifications in the "Transceiver Specifications for Stratix V GX and GS Devices" table.	
		■ Changed the configuration .rbf sizes in the "Uncompressed .rbf Sizes for Stratix V Devices" table.	
		■ Changed the data rate specification for transceiver speed grade 3 in the following tables:	
	3.4	"Transceiver Specifications for Stratix V GX and GS Devices"	
		■ "Stratix V Standard PCS Approximate Maximum Date Rate"	
		■ "Stratix V 10G PCS Approximate Maximum Data Rate"	
July 2015		■ Changed the conditions for reference clock rise and fall time, and added a note to the "Transceiver Specifications for Stratix V GX and GS Devices" table.	
-		■ Added a note to the "Minimum differential eye opening at receiver serial input pins" specification in the "Transceiver Specifications for Stratix V GX and GS Devices" table.	
		■ Changed the t _{CO} maximum value in the "AS Timing Parameters for AS '1 and AS '4 Configurations in Stratix V Devices" table.	
		■ Removed the CDR ppm tolerance specification from the "Transceiver Specifications for Stratix V GX and GS Devices" table.	